



*FOR IMMEDIATE RELEASE*

HDP User Group Announces New Member Company

*Cave Creek, Arizona May 1, 2013.* The High Density Packaging (HDP) User Group headquartered in the United States announces that Elite Material Co., Ltd. (EMC) has become its newest member.

EMC is committed to developing innovative Printed Circuit Board (PCB) base materials with its halogen-free technology which are in line with future market demand and customer requirements, such as ultra-thin core, ultra high thermal conductivity material, IC substrate base material and mid loss, low loss and ultra-low loss high speed materials.

Albert Tung, President for EMC said "We are proud to be a member of HDPUG that will facilitate our work with global OEMs and PCBs to develop the most cost effective and innovative solutions for the electronic industry."

Marshall Andrews Executive Director of HDP User Group said "We are pleased to announce that EMC, one of the premier high tech printed circuit material suppliers has joined our consortium. They are participating in several of our new technology programs, including "*High Frequency Measurement*", which is looking at a uniform test procedure for high speed PWB materials and "*Pad Cratering*" which is evaluating test methods to detect this phenomenon. They are also contributors to our "*PWB Materials Reliability*" project focused on evaluation of next generation high performance laminates and pre-pregs."

**About EMC Corporation**

Elite Material Co., Ltd. (EMC) was established in March, 1992 to design and manufacture base materials for worldwide PCB industry; main products of EMC are copper clad laminates (CCL), prepregs (PP) and mass lamination boards (mass lam PCBs). With "Sustainable Operation" and "Continual Improvement" as their management philosophy. EMC is currently the largest manufacturer of halogen-free base material worldwide and the 7th largest manufacturer of overall laminate materials in the world. <http://www.emctw.com>

**About HDP User Group**

HDP User Group ([www.hdpug.org](http://www.hdpug.org)) is a global research and development organization based in



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[www.hdpug.org](http://www.hdpug.org)

Cave Creek Arizona, is dedicated to “reducing the costs and risks for the Electronics Manufacturing industry when using advanced electronic packaging and assembly”. This international industry led group organizes and conducts R&D programs to address the technical issues facing the industry, including design, printed circuit board manufacturing, electronics assembly, and environmental compliance. HDP User Group maintains additional offices in Austin, Texas; Stockholm, Sweden; and Tokyo, Japan.

For more information, visit HDP User Group on the Internet at [www.hdpug.org](http://www.hdpug.org) or contact Darryl Reiner at [darrylr@hdpug.org](mailto:darrylr@hdpug.org), phone number +1 480-951-1963